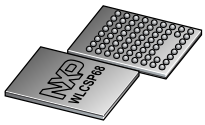

SOT1975-2

WLCSP68, wafer level chip-scale package, 68 terminals; 0.35 mm pitch, 3.78 mm x 3.06 mm x 0.325 mm body (backside coating included)

6 January 2020 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP68
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	25-11-2019
Manufacturer package code	98ASA01559D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.75	3.78	3.81	mm
package width	3.03	3.06	3.09	mm
seated height	-	0.325	0.35	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	68	-	

2 Package outline

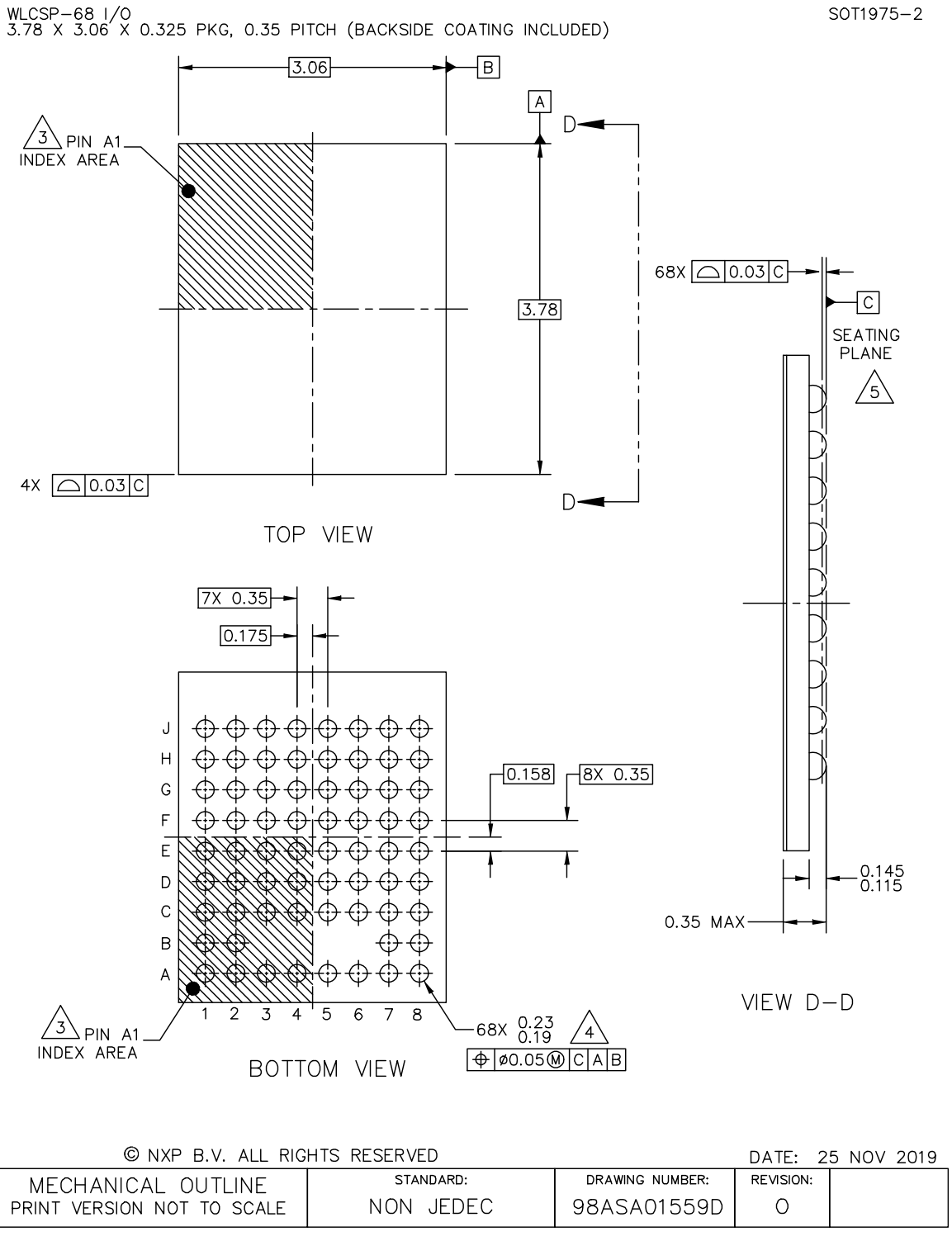

Figure 1. Package outline WLCSP68 (SOT1975-2)

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3 Soldering

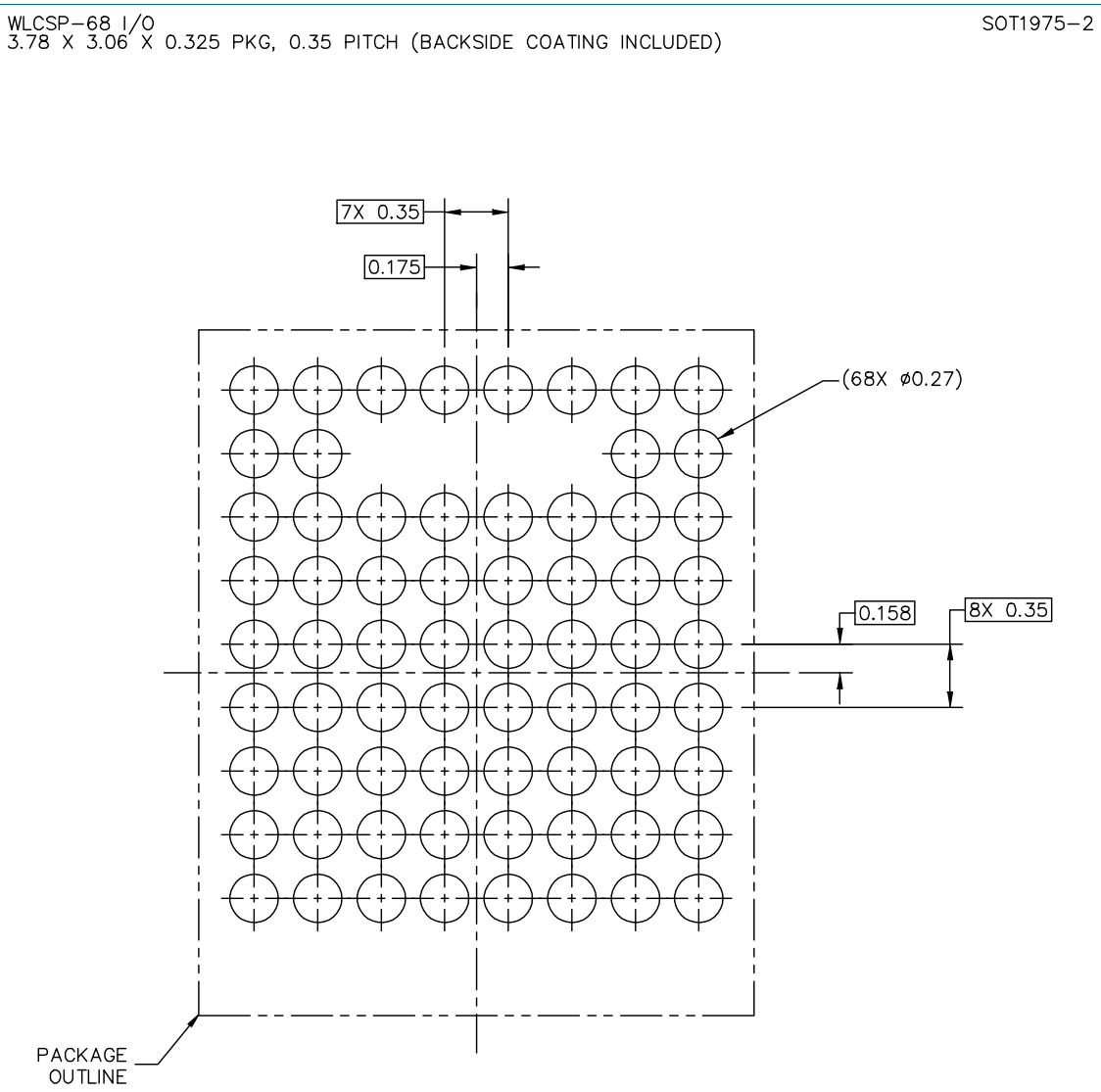

Figure 2. Reflow soldering footprint part1 for WLCSP68 (SOT1975-2)

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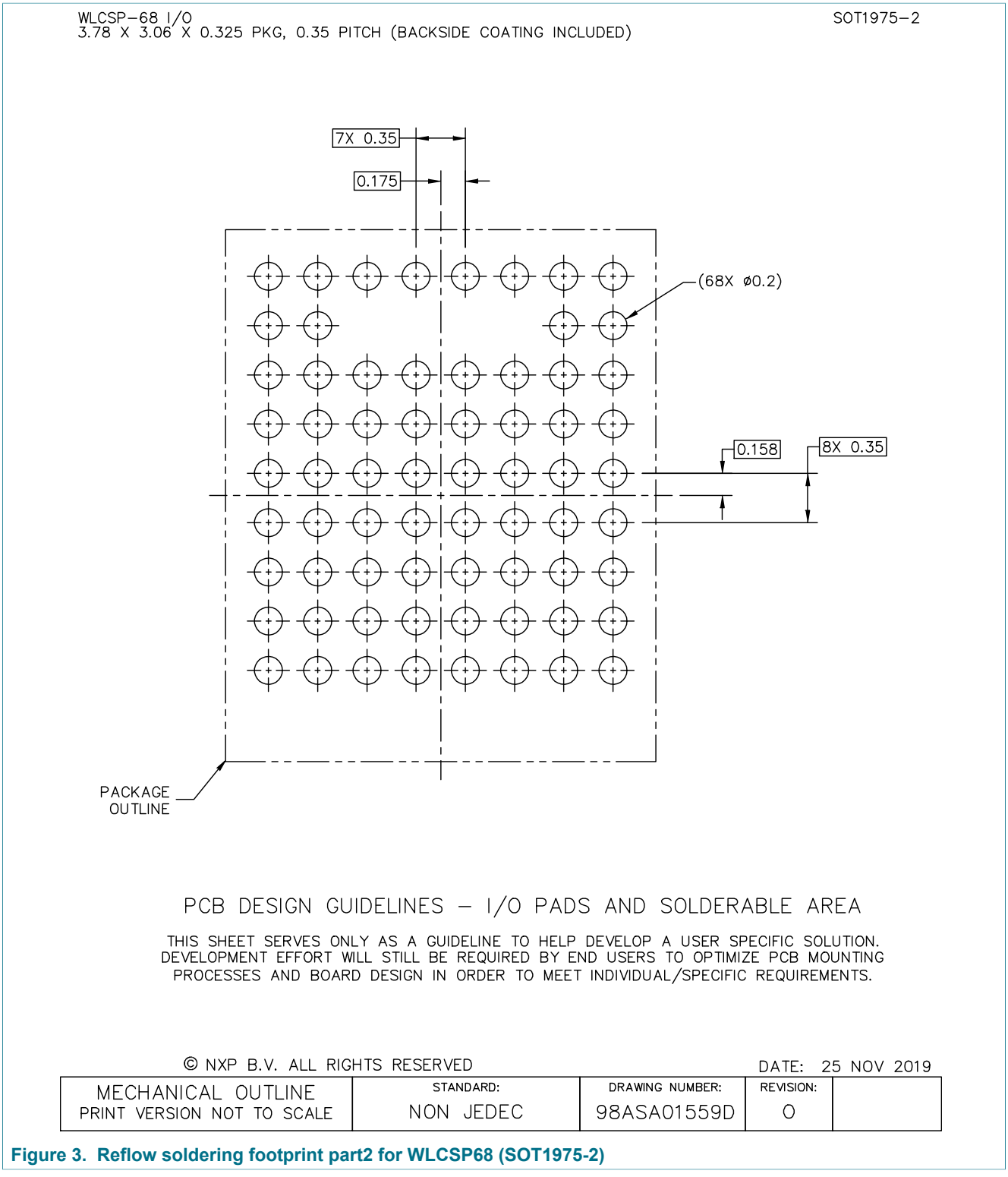

Figure 3. Reflow soldering footprint part2 for WLCSP68 (SOT1975-2)

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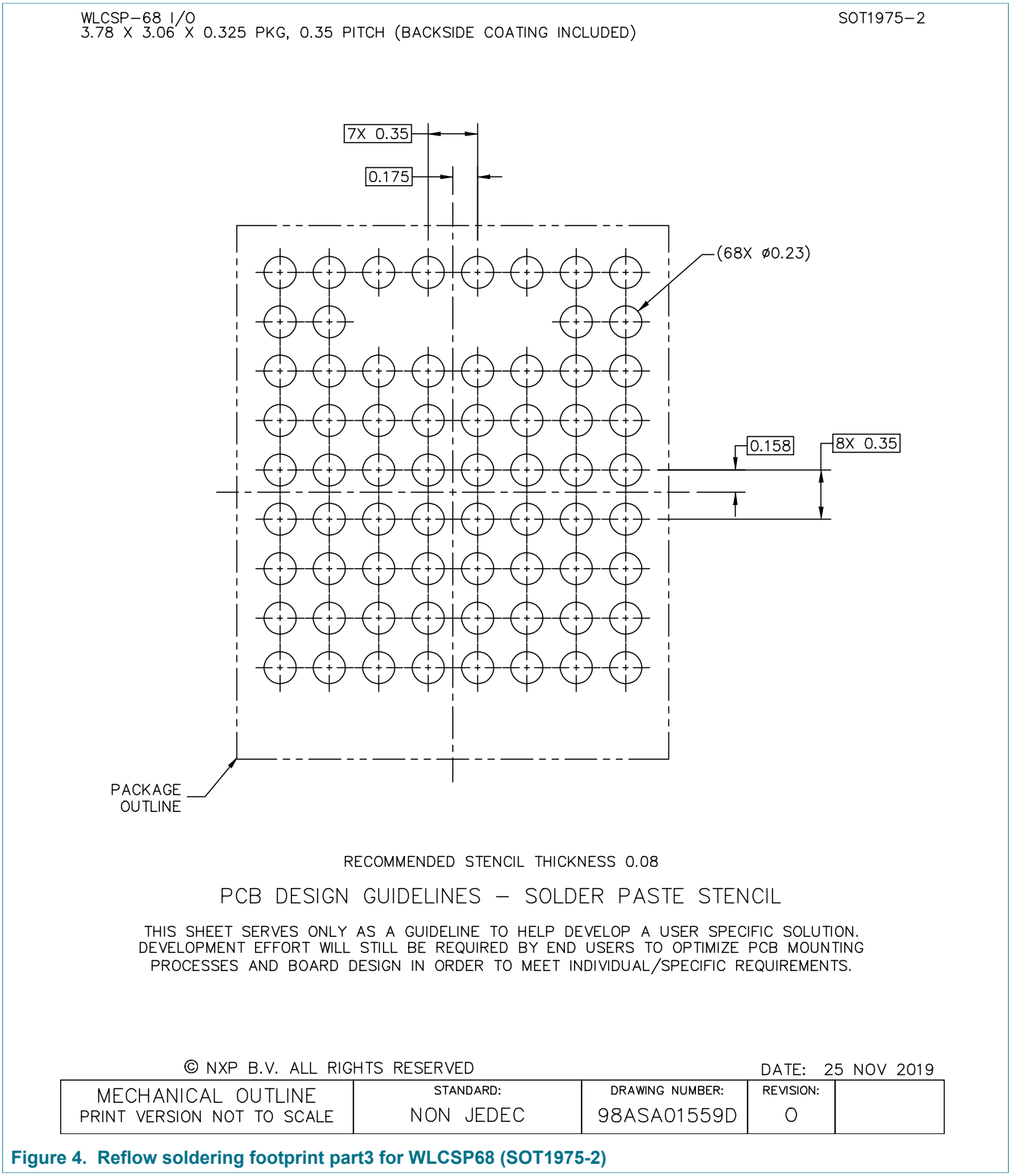

Figure 4. Reflow soldering footprint part3 for WLCSP68 (SOT1975-2)

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WLCSP68, wafer level chip-scale package, 68 terminals; 0.35 mm pitch, 3.78 mm x 3.06 mm x 0.325 mm body (backside coating included)

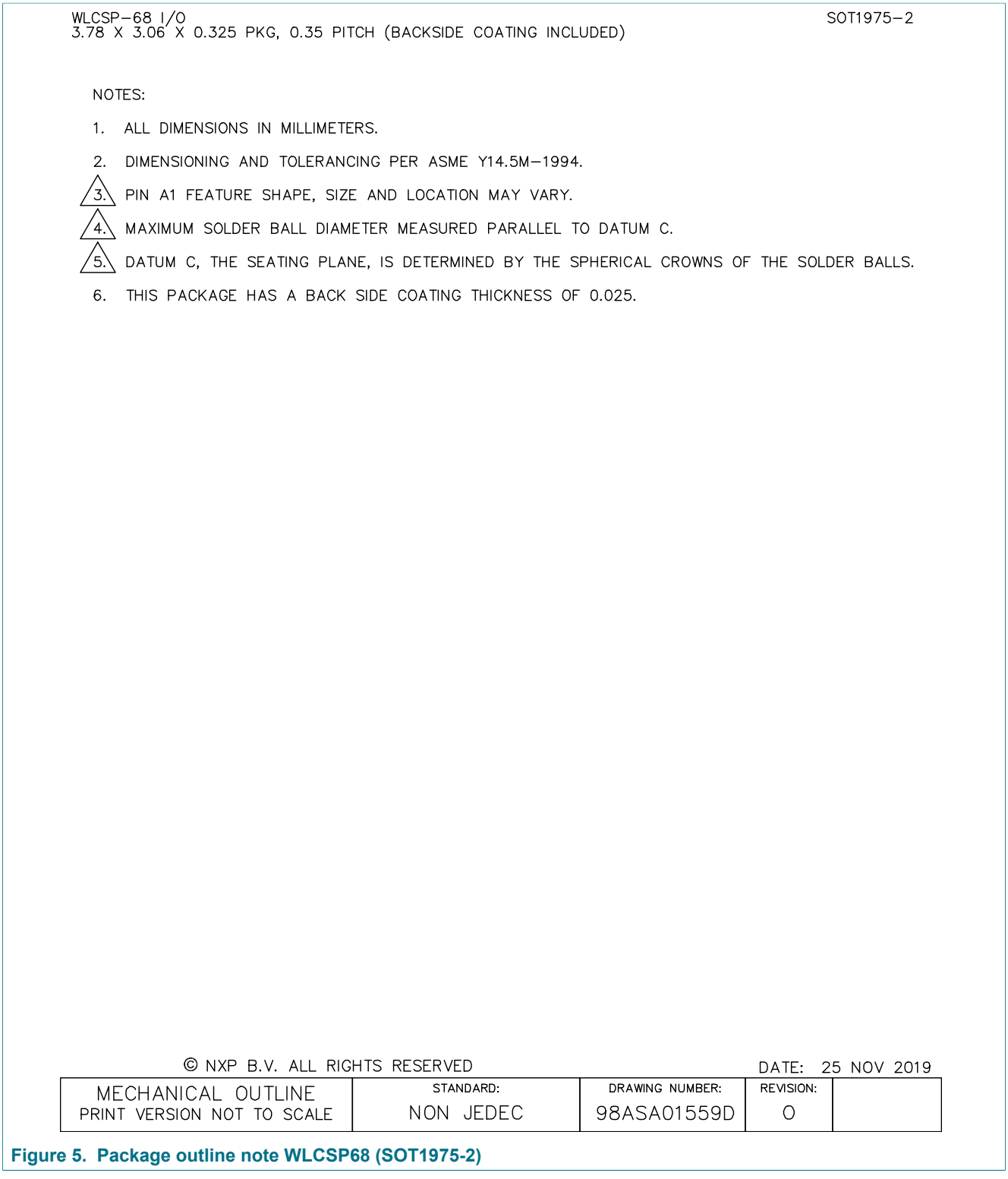

Figure 5. Package outline note WLCSP68 (SOT1975-2)

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4 Legal information

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WLCSP68, wafer level chip-scale package, 68 terminals; 0.35 mm pitch, 3.78 mm x 3.06 mm x 0.325 mm body (backside coating included)

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